

ABSTRACT

METHOD OF MANUFACTURING CHUCK PLATE FOR USE IN ELECTROSTATIC CHUCK

There is provided a method of manufacturing a chuck plate for an electrostatic chuck of good productivity which is free from poor releasing of a wafer (W) which is a to-be-processed substrate, from the initial time of putting the electrostatic chuck to a new use. The method of manufacturing a chuck plate (2) for electrostatic chuck (ES) which is made up of a dielectric body to cover a surface of the chuck main body (1) having electrodes (3a, 3b), includes the steps of: obtaining a sintered body by compression-forming raw material powder (or raw meal) into a predetermined shape and then sintering the same; forming, by means of polishing, such a surface of the sintered body as will come into contact with a substrate to be attracted, into a predetermined surface roughness and flatness; and performing blast processing for selectively removing only ready-to-be-separated particles that come into existence on the surface as a result of the polishing.

FIGURE 2.